

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re application of:** Paul et al.

**Application No.** 10/803,502

**Filed:** March 17, 2004

**Confirmation No.** 5691

**For:** METHOD FOR MAKING DEVICES  
HAVING INTERMETALLIC  
STRUCTURES AND INTERMETALLIC  
DEVICES MADE THEREBY

**Examiner:** Unknown

**Art Unit:** 3729

**Attorney Reference No.** 245-68071-01

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Attorney or Agent  
for Applicant(s)

Date Mailed October 5, 2005

TRANSMITTAL LETTER

Enclosed for filing in the application referenced above are the following:

- ☒ Information Disclosure Statement
- ☒ Form 1449 and references cited thereon
- ☒ The Director is hereby authorized to charge any additional fees that may be required, or credit over-payment, to Deposit Account No. 02-4550. A copy of this sheet is enclosed.
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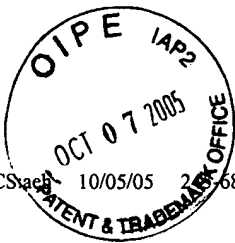
Respectfully submitted,

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By Stacey C. Slater  
Stacey C. Slater  
Registration No. 36,011

cc: Docketing



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PATENT

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**INFORMATION DISCLOSURE STATEMENT  
PURSUANT TO 37 C.F.R. § 1.97(b)(3)**

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Listed on the accompanying form PTO-1449 and enclosed herewith are several English-language documents. Applicants respectfully request that these documents be listed as references cited on the issued patent.

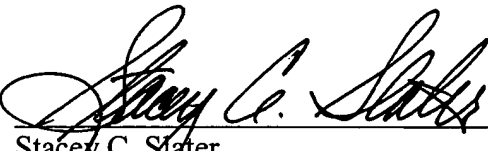
Copies of United States patents and United States published patent applications do not have to be provided to the Patent Office (37 C.F.R. 1.98(a)(2)(ii)). Copies of unpublished U.S. applications do not have to be provided, as long as the application is available on PAIR, as this requirement of 37 C.F.R. § 1.98(a)(2)(iii) has been waived by the United States Patent and Trademark Office pursuant to the Official Gazette Notice on October 19, 2004 (1287 OG 163). Applicants will provide copies of such patents or applications upon request.

Applicants filed this Information Disclosure Statement ("IDS") before the mailing date of a first Office action on the merits. As a result, no fee should be required to file this IDS. However, if the Patent Office determines that a fee is required for Applicants to file this IDS, please charge any such fees, or credit overpayment, to Deposit Account No. 02-4550. A **duplicate** copy of this Information Disclosure Statement is enclosed.

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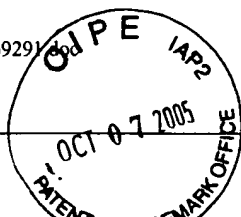
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# INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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<b>Filing Date</b>	March 17, 2004
<b>First Named Inventor</b>	Paul
<b>Art Unit</b>	3729
<b>Examiner Name</b>	Unknown

Examiner's Initials*	Cite No. (optional)	OTHER DOCUMENTS
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